



**THE DATASHEET OF  
TS3A24159YZPR**



# TS3A24159 0.3-Ω 2-Channel SPDT Bidirectional Analog Switch

## Dual-Channel 2:1 Multiplexer and Demultiplexer

### 1 Features

- Specified break-before-make switching
- Low ON-state resistance (0.3 Ω maximum)
- Low charge injection
- Excellent ON-state resistance matching
- Low total harmonic distortion (THD)
- 1.65-V to 3.6-V single-supply operation
- Control inputs are 1.8-V logic compatible
- Latch-up performance exceeds 100 mA per JESD 78, Class II
- ESD performance tested per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)

### 2 Applications

- [Cell phones](#)
- Personal digital assistant (PDAs)
- [Portable instrumentation](#)
- [Audio and video signal routing](#)
- [Low-voltage data-acquisition systems](#)
- [Communication circuits](#)
- [Modems](#)
- Hard drives
- [Computer peripherals](#)
- Wireless terminals and peripherals

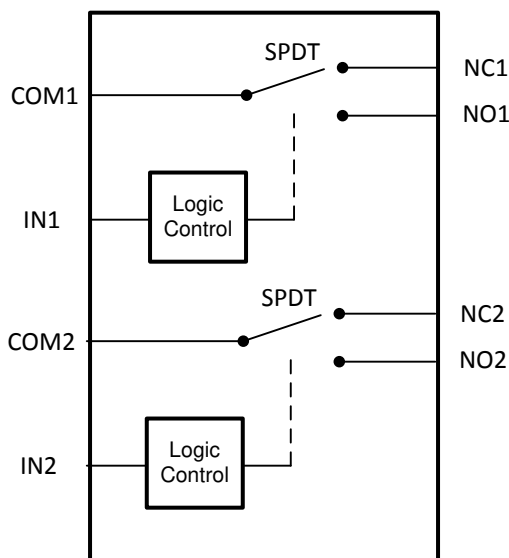
### 3 Description

The TS3A24159 is a 2-channel single-pole double-throw (SPDT) bidirectional analog switch that is designed to operate from 1.65 V to 3.6 V. It offers low ON-state resistance and excellent ON-state resistance matching with the break-before-make feature, to prevent signal distortion during the transferring of a signal from one channel to another. The device has excellent total harmonic distortion (THD) performance, low ON-state resistance, and consumes very low power. These are some of the features that make this device suitable for a variety of markets and many different applications.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TS3A24159	VSSOP (10)	3.00 mm × 3.00 mm
	VSON (10)	3.00 mm × 3.00 mm
	DSBGA (10)	1.86 mm × 1.35 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Functional Block Diagram



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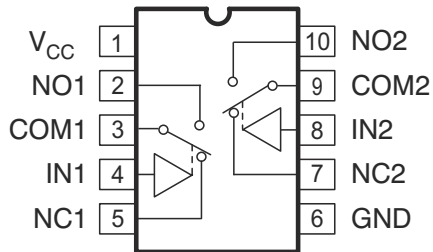
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## 4 Revision History

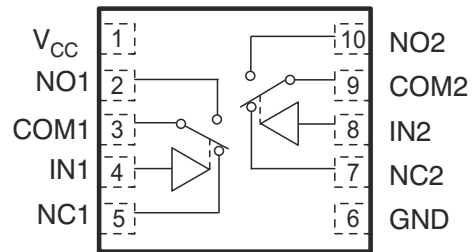
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision G (February 2022) to Revision H (August 2022)	Page
• Changed the maximum $V_{CC}$ from: 3.6 V to: 4 V .....	5
Changes from Revision F (September 2019) to Revision G (February 2022)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
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• Changed the YZP package image view From: Top-Through View To: Bottom View.....	3
Changes from Revision D (July 2015) to Revision E (March 2019)	Page
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• Changed Turnon time $V_{CC}$ (Full) value From: 2.3 V to 2.7 V To: 2.7 V to 3.6 V in <i>Switching Characteristics for a 3-V Supply</i> .....	10
• Changed Turnon time $V_{CC}$ (Full) value From: 2.3 V to 2.7 V To: 2.7 V to 3.6 V in <i>Switching Characteristics for a 2.5-V Supply</i> .....	10
Changes from Revision C (February 2008) to Revision D (March 2015)	Page
• Added <i>Pin Configuration and Functions</i> section, <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	1
• Changed $V+$ to $V_{CC}$ throughout the document to meet JEDEC standards.....	1

## 5 Pin Configuration and Functions



**Figure 5-1. DGS Package, 10-Pin VSSOP (Top View)**

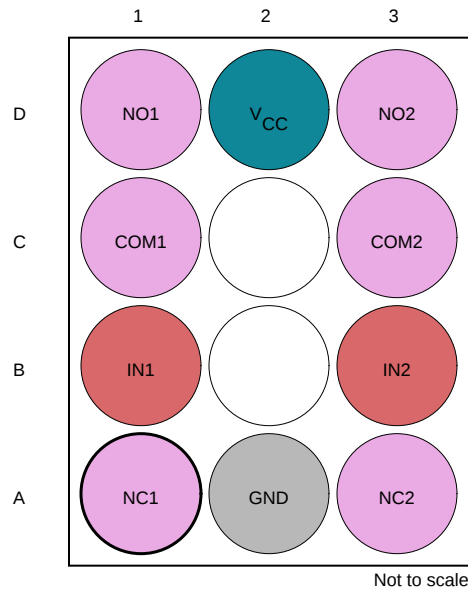


**Figure 5-2. DRC Package, 10-Pin VSON (Top View)**

**Table 5-1. Pin Functions – VSSOP and VSON**

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NO.	NAME		
1	V <sub>CC</sub>	—	Power supply
2	NO1	I/O	Normally open signal path
3	COM1	I/O	Common signal path
4	IN1	I	Digital control to connect COM to NO or NC
5	NC1	I/O	Normally closed signal path
6	GND	—	Ground
7	NC2	I/O	Normally closed signal path
8	IN2	I	Digital control to connect COM to NO or NC
9	COM2	I/O	Common signal path
10	NO2	I/O	Normally open signal path

(1) I = input, O = output



**Figure 5-3. YZP Package, 10-Pin DSBGA (Bottom View)**

Legend	
Input or Output	Input
Ground	Power

**Table 5-2. Pin Functions – DSBGA**

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NO.	NAME		
A1	NC1	I/O	Normally closed signal path
A2	GND	—	Ground
A3	NC2	I/O	Normally closed signal path
B1	IN1	I	Digital control to connect COM to NO or NC
B3	IN2	I	Digital control to connect COM to NO or NC
C1	COM1	I/O	Common signal path
C3	COM2	I/O	Common signal path
D1	NO1	I/O	Normally open signal path
D2	V <sub>CC</sub>	—	Power supply
D3	NO2	I/O	Normally open signal path

(1) I = input, O = output

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup> <sup>(2)</sup>

		MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage <sup>(3)</sup>	-0.5	4	V	
V <sub>NC</sub> V <sub>NO</sub> V <sub>COM</sub>	Signal voltage <sup>(3)</sup> <sup>(4)</sup>	-0.5	V <sub>CC</sub> + 0.5	V	
I <sub>I/O</sub> K	Analog port diode current	V <sub>NC</sub> , V <sub>NO</sub> , V <sub>COM</sub> < 0		-50      50	mA
I <sub>NC</sub> I <sub>NO</sub> I <sub>COM</sub>	ON-state switch current	V <sub>NC</sub> , V <sub>NO</sub> , V <sub>COM</sub> = 0 to V <sub>CC</sub>		-300      300	mA
	ON-state peak switch current <sup>(5)</sup>			-500      500	
V <sub>IN</sub>	Digital input voltage	-0.5	3.6	V	
I <sub>IK</sub>	Digital input clamp current <sup>(3)</sup>	V <sub>I</sub> < 0		-50	mA
I <sub>CC</sub>	Continuous current through V <sub>CC</sub>		100	mA	
I <sub>GND</sub>	Continuous current through GND	-100		mA	
T <sub>stg</sub>	Storage temperature	-65	150	°C	

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.
- (3) All voltages are with respect to ground, unless otherwise specified.
- (4) This value is limited to 5.5 V maximum.
- (5) Pulse at 1-ms duration <10% duty cycle.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	2000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 or ANSI/ESDA/JEDEC JS-002 <sup>(2)</sup>	1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply Voltage	1.65	3.6	V
V <sub>NC</sub> V <sub>NO</sub> V <sub>COM</sub>	Signal Voltage	0	V <sub>CC</sub>	V
V <sub>IN</sub>	Digital Input Voltage	0	V <sub>CC</sub>	V

## 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TS3A24159			UNIT
		DGS (VSSOP)	DRC (VSON)	YZP (DSBGA)	
		10 PINS	10 PINS	10 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	154	49.4	90.9	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	37.9	71.2	0.3	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	83.6	23.8	8.3	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	1.4	2.2	3.2	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	82.2	23.8	8.3	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	N/A	6.1	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics for 3-V Supply

V<sub>CC</sub> = 2.7 V to 3.6 V, T<sub>A</sub> = –40°C to 85°C (unless otherwise noted) <sup>(1)</sup>

PARAMETER	TEST CONDITIONS	T <sub>A</sub>	V <sub>CC</sub>	MIN	TYP	MAX	UNIT
<b>ANALOG SWITCH</b>							
Analog signal range	V <sub>COM</sub> , V <sub>NO</sub> , V <sub>NC</sub>			0		V <sub>CC</sub>	V
Peak ON resistance	r <sub>peak</sub> 0 ≤ (V <sub>NO</sub> or V <sub>NC</sub> ) ≤ V <sub>CC</sub> , I <sub>COM</sub> = –100 mA,	Switch ON, See <a href="#">Figure 7-1</a>	25°C Full	2.7 V	0.2	0.3 0.35	Ω
ON-state resistance	r <sub>on</sub> V <sub>NO</sub> or V <sub>NC</sub> = 2 V, I <sub>COM</sub> = –100 mA,	Switch ON, See <a href="#">Figure 7-1</a>	25°C Full	2.7 V	0.26	0.3 0.34	Ω
ON-state resistance match between channels	Δr <sub>on</sub> V <sub>NO</sub> or V <sub>NC</sub> = 2 V, 0.8 V, I <sub>COM</sub> = –100 mA,	Switch ON, See <a href="#">Figure 7-1</a>	25°C Full	2.7 V	0.01	0.05 0.05	Ω
ON-state resistance flatness	r <sub>on(flat)</sub> 0 ≤ (V <sub>NO</sub> or V <sub>NC</sub> ) ≤ V <sub>CC</sub> , I <sub>COM</sub> = –100 mA, V <sub>NO</sub> or V <sub>NC</sub> = 2 V, 0.8 V, I <sub>COM</sub> = –100 mA,	Switch ON, See <a href="#">Figure 7-1</a>	25°C Full	2.7 V	0.13	0.01 0.04 0.05	Ω
NC, NO OFF leakage current	I <sub>NC(OFF)</sub> , I <sub>NO(OFF)</sub> V <sub>NC</sub> or V <sub>NO</sub> = 1 V, V <sub>COM</sub> = 3 V, or V <sub>NC</sub> or V <sub>NO</sub> = 3 V, V <sub>COM</sub> = 1 V,	Switch OFF, See <a href="#">Figure 7-2</a>	25°C Full	3.6 V	–10	10 50	nA
NC, NO ON leakage current	I <sub>NC(ON)</sub> , I <sub>NO(ON)</sub> V <sub>NC</sub> or V <sub>NO</sub> = 1 V, V <sub>COM</sub> = Open, or V <sub>NC</sub> or V <sub>NO</sub> = 3 V, V <sub>COM</sub> = Open,	Switch ON, See <a href="#">Figure 7-3</a>	25°C Full	3.6 V	–10	10 100	nA
COM ON leakage current	I <sub>COM(ON)</sub> V <sub>NC</sub> or V <sub>NO</sub> = Open, V <sub>COM</sub> = 1 V, or V <sub>NC</sub> or V <sub>NO</sub> = Open, V <sub>COM</sub> = 3 V,	Switch ON, See <a href="#">Figure 7-3</a>	25°C Full	3.6 V	–10	10 100	nA
<b>DIGITAL CONTROL INPUTS (IN1, IN2)<sup>(2)</sup></b>							
Input logic high	V <sub>IH</sub>		Full		1.4		V
Input logic low	V <sub>IL</sub>		Full			0.5	V
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = 3.6 V or 0	25°C Full	3.6 V	–40	5 40 50	nA

## 6.5 Electrical Characteristics for 3-V Supply (continued)

$V_{CC} = 2.7\text{ V to }3.6\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted) <sup>(1)</sup>

PARAMETER	TEST CONDITIONS	$T_A$	$V_{CC}$	MIN	TYP	MAX	UNIT
<b>DYNAMIC</b>							
Charge injection	$Q_C$ $V_{GEN} = 0$ , $R_{GEN} = 0$ , $C_L = 1\text{ nF}$ , See <a href="#">Figure 7-10</a>	25°C	3 V		9		pC
NC, NO OFF capacitance	$C_{NC(OFF)}$ , $C_{NO(OFF)}$ $V_{NC}$ or $V_{NO} = V_{CC}$ or GND, Switch OFF,	25°C	3 V		90		pF
NC, NO ON capacitance	$C_{NC(ON)}$ , $C_{NO(ON)}$ $V_{NC}$ or $V_{NO} = V_{CC}$ or GND, Switch ON,	25°C	3 V		224		pF
COM ON capacitance	$C_{COM(ON)}$ $V_{COM} = V_{CC}$ or GND, Switch ON,	25°C	3 V		250		pF
Digital input capacitance	$C_I$ $V_{IN} = V_{CC}$ or GND,	25°C	3 V		2		pF
Bandwidth	$BW$ $R_L = 50\ \Omega$ , Switch ON,	25°C	3 V		23		MHz
OFF isolation	$O_{ISO}$ $R_L = 50\ \Omega$ , $f = 1\text{ MHz}$ ,	25°C	3 V		-72		dB
Crosstalk	$X_{TALK}$ $R_L = 50\ \Omega$ , $f = 1\text{ MHz}$ ,	25°C	3 V		-96		dB
Total harmonic distortion	$THD$ $R_L = 600\ \Omega$ , $C_L = 50\text{ pF}$ , $f = 20\text{ Hz to }20\text{ kHz}$ , See <a href="#">Figure 7-11</a>	25°C	3 V		0.003%		
<b>SUPPLY</b>							
Positive supply current	$I_{CC}$ $V_{IN} = V_{CC}$ or GND	25°C	3.6 V		15	100	nA
		Full			1		$\mu\text{A}$

- (1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum  
 (2) All unused digital inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, [Implications of Slow or Floating CMOS Inputs](#).

## 6.6 Electrical Characteristics for 2.5-V Supply

$V_{CC} = 2.3\text{ V to }2.7\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted) <sup>(1)</sup>

PARAMETER	TEST CONDITIONS	$T_A$	$V_{CC}$	MIN	TYP	MAX	UNIT
<b>ANALOG SWITCH</b>							
Analog signal range	$V_{COM}$ , $V_{NO}$ , $V_{NC}$			0		$V_{CC}$	V
Peak ON resistance	$r_{peak}$ $0 \leq (V_{NO} \text{ or } V_{NC}) \leq V_{CC}$ , $I_{COM} = -8\text{ mA}$ ,	25°C	2.3 V			0.35	$\Omega$
		Full				0.45	
ON-state resistance	$r_{on}$ $V_{NO}$ or $V_{NC} = 1.8\text{ V}$ , $I_{COM} = -8\text{ mA}$ ,	25°C	2.3 V				$\Omega$
		Full				0.4	
ON-state resistance match between channels	$\Delta r_{on}$ $V_{NO}$ or $V_{NC} = 1.8\text{ V}, 0.8\text{ V}$ , $I_{COM} = -8\text{ mA}$ ,	25°C	2.3 V		0.01	0.05	$\Omega$
		Full			0.05	0.05	
ON-state resistance flatness	$r_{on(Flat)}$ $0 \leq (V_{NO} \text{ or } V_{NC}) \leq V_{CC}$ , $I_{COM} = -8\text{ mA}$ ,	25°C	2.3 V			0.05	$\Omega$
		25°C				0.03	
NC, NO OFF leakage current	$I_{NC(OFF)}$ , $I_{NO(OFF)}$ $V_{NC}$ or $V_{NO} = 0.5\text{ V}, V_{COM} = 2.2\text{ V}$ , or $V_{NC}$ or $V_{NO} = 2.2\text{ V}, V_{COM} = 0.5\text{ V}$ ,	25°C	2.7 V		-10	10	nA
		Full			-50	50	

## 6.6 Electrical Characteristics for 2.5-V Supply (continued)

 $V_{CC} = 2.3\text{ V to }2.7\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted) <sup>(1)</sup>

PARAMETER	TEST CONDITIONS	$T_A$	$V_{CC}$	MIN	TYP	MAX	UNIT	
NC, NO ON leakage current	$I_{NC(ON)}$ , $I_{NO(ON)}$ $V_{NC}$ or $V_{NO} = 0.5\text{ V}$ , $V_{COM} = \text{Open}$ , or $V_{NC}$ or $V_{NO} = 2.2\text{ V}$ , $V_{COM} = \text{Open}$ ,	Switch ON, See <a href="#">Figure 7-3</a>	2.7 V	-10		10	nA	
		25°C						
		Full		-100		100		
ANALOG SWITCH (continued)								
COM ON leakage current	$I_{COM(ON)}$ $V_{NC}$ or $V_{NO} = \text{Open}$ , $V_{COM} = 0.5\text{ V}$ , or $V_{NC}$ or $V_{NO} = \text{Open}$ , $V_{COM} = 2.2\text{ V}$ ,	Switch ON, See <a href="#">Figure 7-3</a>	2.7 V	-10		10	nA	
		25°C						
		Full		-100		100		
<b>DIGITAL CONTROL INPUTS (IN1, IN2)<sup>(2)</sup></b>								
Input logic high	$V_{IH}$		Full	1.25			V	
Input logic low	$V_{IL}$		Full			0.5	V	
Input leakage current	$I_{IH}$ , $I_{IL}$ $V_I = 2.7\text{ V or }0$	25°C	2.7 V	-40	5	40	nA	
		Full						-50
<b>DYNAMIC</b>								
Charge injection	$Q_C$ $V_{GEN} = 0$ , $R_{GEN} = 0$ ,	$C_L = 1\text{ nF}$ , See <a href="#">Figure 7-10</a>	25°C	2.5 V		8	pC	
NC, NO OFF capacitance	$C_{NC(OFF)}$ , $C_{NO(OFF)}$ $V_{NC}$ or $V_{NO} = V_{CC}$ or GND, Switch OFF,	See <a href="#">Figure 7-4</a>	25°C	2.5 V		90	pF	
NC, NO ON capacitance	$C_{NC(ON)}$ , $C_{NO(ON)}$ $V_{NC}$ or $V_{NO} = V_{CC}$ or GND, Switch ON,	See <a href="#">Figure 7-4</a>	25°C	2.5 V		250	pF	
COM ON capacitance	$C_{COM(ON)}$ $V_{COM} = V_{CC}$ or GND, Switch ON,	See <a href="#">Figure 7-4</a>	25°C	2.5 V		250	pF	
Digital input capacitance	$C_I$ $V_I = V_{CC}$ or GND,	See <a href="#">Figure 7-4</a>	25°C	2.5 V		2	pF	
Bandwidth	$BW$ $R_L = 50\ \Omega$ , Switch ON,	See <a href="#">Figure 7-7</a>	25°C	2.5 V		23	MHz	
OFF isolation	$O_{ISO}$ $R_L = 50\ \Omega$ , $f = 1\text{ MHz}$ ,	See <a href="#">Figure 7-8</a>	25°C	2.5 V		-72	dB	
Crosstalk	$X_{TALK}$ $R_L = 50\ \Omega$ , $f = 1\text{ MHz}$ ,	See <a href="#">Figure 7-9</a>	25°C	2.5 V		-96	dB	
Total harmonic distortion	$THD$ $R_L = 600\ \Omega$ , $C_L = 50\text{ pF}$ ,	$f = 20\text{ Hz to }20\text{ kHz}$ , See <a href="#">Figure 7-11</a>	25°C	2.5 V		0.003%		
<b>SUPPLY</b>								
Positive supply current	$I_{CC}$ $V_I = V_{CC}$ or GND	25°C	2.7 V			10	100	nA
		Full				700		

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.

(2) All unused digital inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, [Implications of Slow or Floating CMOS Inputs](#).

## 6.7 Electrical Characteristics for 1.8-V Supply

 $V_{CC} = 1.65\text{ V to }1.95\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted) <sup>(1)</sup>

PARAMETER		TEST CONDITIONS		$T_A$	$V_{CC}$	MIN	TYP	MAX	UNIT
<b>ANALOG SWITCH</b>									
Analog signal range	$V_{COM}, V_{NO}, V_{NC}$					0		$V_{CC}$	V
Peak ON resistance	$r_{peak}$	$0 \leq (V_{NO} \text{ or } V_{NC}) \leq V_{CC}$ , $I_{COM} = -2\text{ mA}$ ,	Switch ON, See <a href="#">Figure 7-1</a>	25°C Full	1.65 V		0.4	0.7 0.8	$\Omega$
ON-state resistance	$r_{on}$	$V_{NO} \text{ or } V_{NC} = 1.5\text{ V}$ , $I_{COM} = -2\text{ mA}$ ,	Switch ON, See <a href="#">Figure 7-1</a>	25°C Full	1.65 V		0.3	0.45 0.5	$\Omega$
ANALOG SWITCH (continued)									
ON-state resistance match between channels	$\Delta r_{on}$	$V_{NO} \text{ or } V_{NC} = 0.6\text{ V}, 1.5\text{ V}$ , $I_{COM} = -2\text{ mA}$ ,	Switch ON, See <a href="#">Figure 7-1</a>	25°C Full	1.65 V		0.02	0.04 0.05	$\Omega$
ON-state resistance flatness	$r_{on(Flat)}$	$0 \leq (V_{NO} \text{ or } V_{NC}) \leq V_{CC}$ , $I_{COM} = -2\text{ mA}$ , $V_{NO} \text{ or } V_{NC} = 0.6\text{ V}, 1.5\text{ V}$ , $I_{COM} = -8\text{ mA}$ ,	Switch ON, See <a href="#">Figure 7-1</a> Switch ON, See <a href="#">Figure 7-1</a>	25°C 25°C Full	1.65 V		0.13	0.08 0.15 0.2	$\Omega$
NC, NO OFF leakage current	$I_{NC(OFF)}, I_{NO(OFF)}$	$V_{NC} \text{ or } V_{NO} = 0.3\text{ V}, V_{COM} = 1.65\text{ V}$ , or $V_{NC} \text{ or } V_{NO} = 1.65\text{ V}, V_{COM} = 0.3\text{ V}$ ,	Switch OFF, See <a href="#">Figure 7-2</a>	25°C Full	1.95	-10 -50		10 50	nA
NC, NO ON leakage current	$I_{NC(ON)}, I_{NO(ON)}$	$V_{NC} \text{ or } V_{NO} = 0.3\text{ V}, V_{COM} = \text{Open}$ , or $V_{NC} \text{ or } V_{NO} = 1.65\text{ V}, V_{COM} = \text{Open}$ ,	Switch ON, See <a href="#">Figure 7-3</a>	25°C Full	1.95 V	-10 -100		10 100	nA
COM ON leakage current	$I_{COM(ON)}$	$V_{NC} \text{ or } V_{NO} = \text{Open}, V_{COM} = 0.3\text{ V}$ , or $V_{NC} \text{ or } V_{NO} = \text{Open}, V_{COM} = 1.65\text{ V}$ ,	Switch ON, See <a href="#">Figure 7-3</a>	25°C Full	1.95 V	-10 -100		10 100	nA
<b>DIGITAL CONTROL INPUTS (IN1, IN2)<sup>(2)</sup></b>									
Input logic high	$V_{IH}$			Full		1			V
Input logic low	$V_{IL}$			Full				0.4	V
Input leakage current	$I_{IH}, I_{IL}$	$V_I = 1.95\text{ V or }0$		25°C Full	1.95 V	-40 -50	5	40 50	nA
<b>DYNAMIC</b>									
Charge injection	$Q_C$	$V_{GEN} = 0$ , $R_{GEN} = 0$ ,	$C_L = 1\text{ nF}$ , See <a href="#">Figure 7-10</a>	25°C	1.8 V		5		pC
NC, NO OFF capacitance	$C_{NC(OFF)}, C_{NO(OFF)}$	$V_{NC} \text{ or } V_{NO} = V_{CC} \text{ or } \text{GND}$ , Switch OFF,	See <a href="#">Figure 7-4</a>	25°C	1.8 V		90		pF
NC, NO ON capacitance	$C_{NC(ON)}, C_{NO(ON)}$	$V_{NC} \text{ or } V_{NO} = V_{CC} \text{ or } \text{GND}$ , Switch ON,	See <a href="#">Figure 7-4</a>	25°C	1.8 V		250		pF
COM ON capacitance	$C_{COM(ON)}$	$V_{COM} = V_{CC} \text{ or } \text{GND}$ , Switch ON,	See <a href="#">Figure 7-4</a>	25°C	1.8 V		250		pF
Digital input capacitance	$C_{IN}$	$V_I = V_{CC} \text{ or } \text{GND}$ ,	See <a href="#">Figure 7-4</a>	25°C	1.8 V		2		pF
Bandwidth	BW	$R_L = 50\ \Omega$ , Switch ON,	See <a href="#">Figure 7-7</a>	25°C	1.8 V		23		MHz
OFF isolation	$O_{ISO}$	$R_L = 50\ \Omega$ , $f = 1\text{ MHz}$ ,	See <a href="#">Figure 7-8</a>	25°C	1.8 V	-73			dB
Crosstalk	$X_{TALK}$	$R_L = 50\ \Omega$ , $f = 1\text{ MHz}$ ,	See <a href="#">Figure 7-9</a>	25°C	1.8 V	-97			dB

## 6.7 Electrical Characteristics for 1.8-V Supply (continued)

$V_{CC} = 1.65\text{ V to }1.95\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted) <sup>(1)</sup>

PARAMETER	TEST CONDITIONS	$T_A$	$V_{CC}$	MIN	TYP	MAX	UNIT
Total harmonic distortion THD	$R_L = 600\ \Omega$ , $C_L = 50\ \text{pF}$ ,  $f = 20\ \text{Hz to }20\ \text{kHz}$ , See <a href="#">Figure 7-11</a>	25°C	1.8 V	0.005%			
<b>SUPPLY</b>							
Positive supply current $I_{CC}$	$V_I = V_{CC}$ or GND	25°C	1.95 V	100		50	nA
		Full		700			

- (1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum  
(2) All unused digital inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, [Implications of Slow or Floating CMOS Inputs](#).

## 6.8 Switching Characteristics for a 3-V Supply

$V_{CC} = 2.7\text{ V to }3.6\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted) <sup>(1)</sup>

PARAMETER	TEST CONDITIONS	$T_A$	$V_{CC}$	MIN	TYP	MAX	UNIT
Dynamic							
Turnon time $t_{ON}$	$V_{COM} = V_{CC}$ , $R_L = 50\ \Omega$ ,  $C_L = 35\ \text{pF}$ , See <a href="#">Figure 7-5</a>	25°C	3.0 V	20		35	ns
		Full	2.7 V to 3.6 V	40			
Turnoff time $t_{OFF}$	$V_{COM} = V_{CC}$ , $R_L = 50\ \Omega$ ,  $C_L = 35\ \text{pF}$ , See <a href="#">Figure 7-5</a>	25°C	3.0 V	12		25	ns
		Full	2.7 V to 3.6 V	30			
Break-before-make time $t_{BBM}$	$V_{NC} = V_{NO} = V_{CC}$ , $R_L = 50\ \Omega$ ,  $C_L = 35\ \text{pF}$ , See <a href="#">Figure 7-6</a>	25°C	3.0 V	1	10	25	ns
		Full	2.7 V to 3.6 V	0.5		30	

- (1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.

## 6.9 Switching Characteristics for a 2.5-V Supply

$V_{CC} = 2.3\text{ V to }2.7\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted) <sup>(1)</sup>

PARAMETER	TEST CONDITIONS	$T_A$	$V_{CC}$	MIN	TYP	MAX	UNIT
Dynamic							
Turnon time $t_{ON}$	$V_{COM} = V_{CC}$ , $R_L = 50\ \Omega$ ,  $C_L = 35\ \text{pF}$ , See <a href="#">Figure 7-5</a>	25°C	2.5 V	23		45	ns
		Full	2.3 V to 2.7 V	50			
Turnoff time $t_{OFF}$	$V_{COM} = V_{CC}$ , $R_L = 50\ \Omega$ ,  $C_L = 35\ \text{pF}$ , See <a href="#">Figure 7-5</a>	25°C	2.5 V	17		27	ns
		Full	2.3 V to 2.7 V	30			
Break-before-make time $t_{BBM}$	$V_{NC} = V_{NO} = V_{CC}$ , $R_L = 50\ \Omega$ ,  $C_L = 35\ \text{pF}$ , See <a href="#">Figure 7-6</a>	25°C	2.5 V	2	14	30	ns
		Full	2.3 V to 2.7 V	1		35	

- (1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.

## 6.10 Switching Characteristics for a 1.8-V Supply

$V_{CC} = 1.65\text{ V to }1.95\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted) <sup>(1)</sup>

PARAMETER	TEST CONDITIONS	$T_A$	$V_{CC}$	MIN	TYP	MAX	UNIT		
Dynamic									
Turnon time	$t_{ON}$	$V_{COM} = V_{CC}$ , $R_L = 50\ \Omega$	$C_L = 35\text{ pF}$ , See <a href="#">Figure 7-5</a>	25°C	1.8 V	53	75	ns	
				Full	1.65 V to 1.96 V		80		
Turnoff time	$t_{OFF}$	$V_{COM} = V_{CC}$ , $R_L = 50\ \Omega$	$C_L = 35\text{ pF}$ , See <a href="#">Figure 7-5</a>	25°C	1.8 V	24	35	ns	
				Full	1.65 V to 1.96 V		40		
Break-before-make time	$t_{BBM}$	$V_{NC} = V_{NO} = V_{CC}$ , $R_L = 50\ \Omega$	$C_L = 35\text{ pF}$ , See <a href="#">Figure 7-6</a>	25°C	1.8 V	2	30	40	ns
				Full	1.65 V to 1.96 V	1		50	

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.

## 6.11 Typical Characteristics

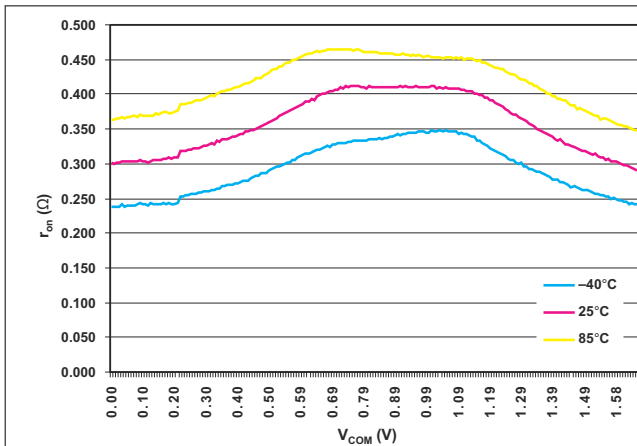


Figure 6-1.  $r_{on}$  vs  $V_{COM}$  ( $V_{CC} = 1.65$  V)

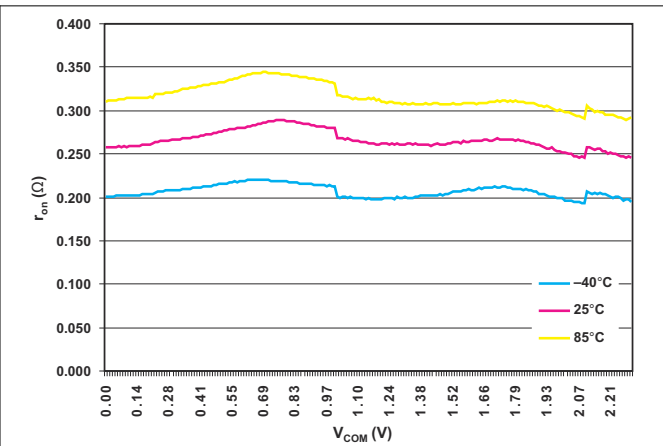


Figure 6-2.  $r_{on}$  vs  $V_{COM}$  ( $V_{CC} = 2.3$  V)

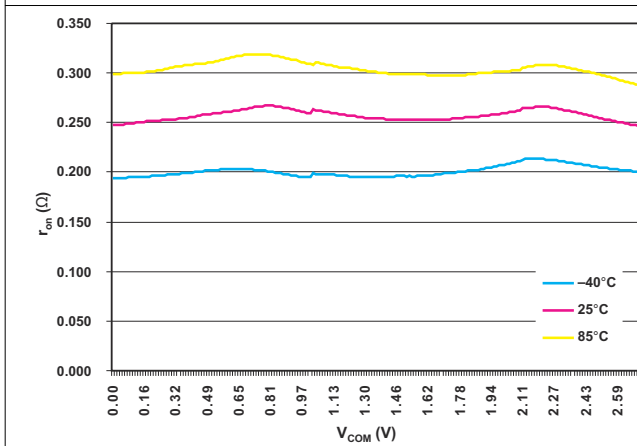


Figure 6-3.  $r_{on}$  vs  $V_{COM}$  ( $V_{CC} = 2.7$  V)

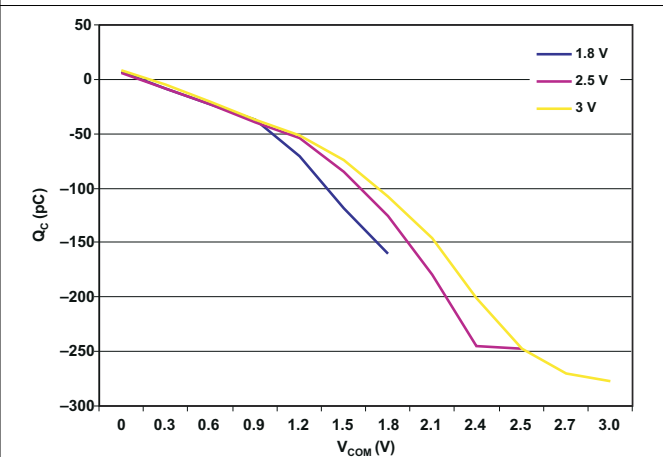


Figure 6-4. Charge Injection ( $Q_C$ ) vs  $V_{COM}$  ( $T_A = 25^\circ\text{C}$ )

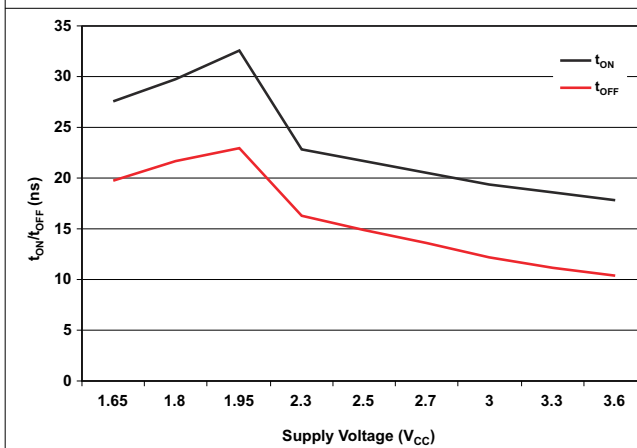


Figure 6-5.  $t_{ON}$  and  $t_{OFF}$  vs Supply Voltage ( $T_A = 25^\circ\text{C}$ )

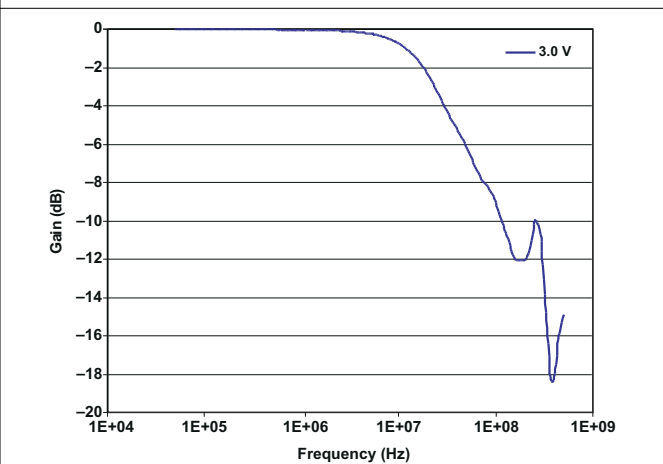
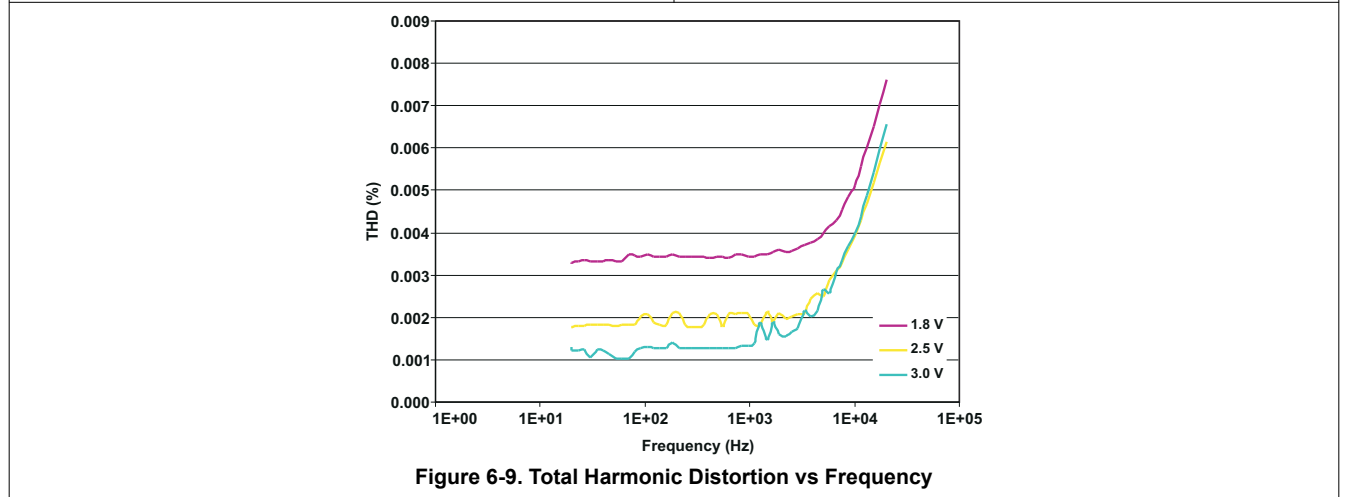
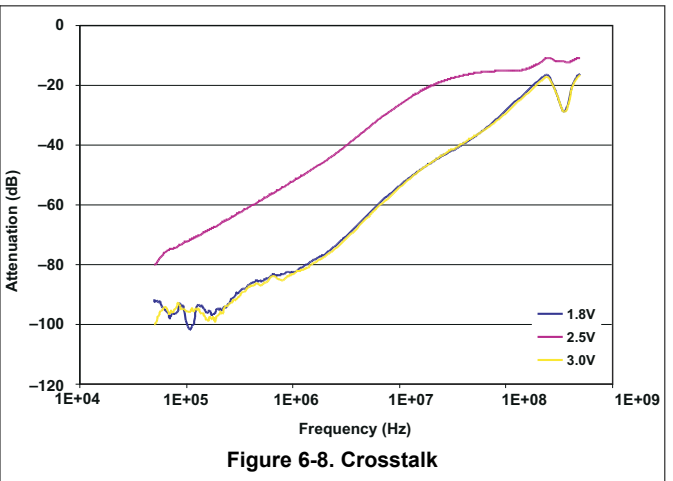
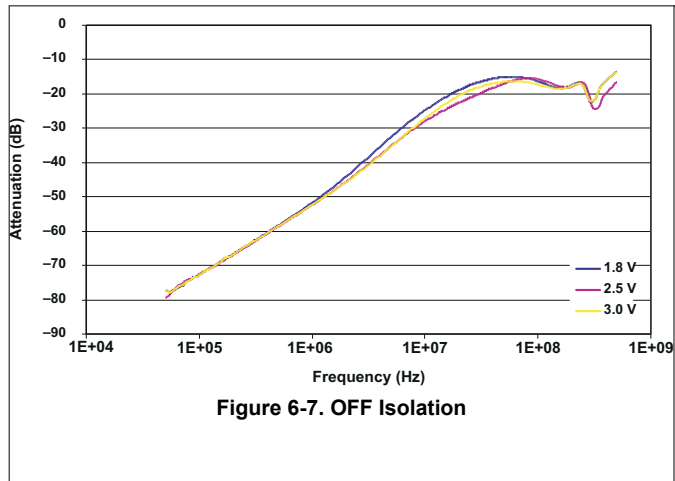


Figure 6-6. Bandwidth

### 6.11 Typical Characteristics (continued)



## 7 Parameter Measurement Information

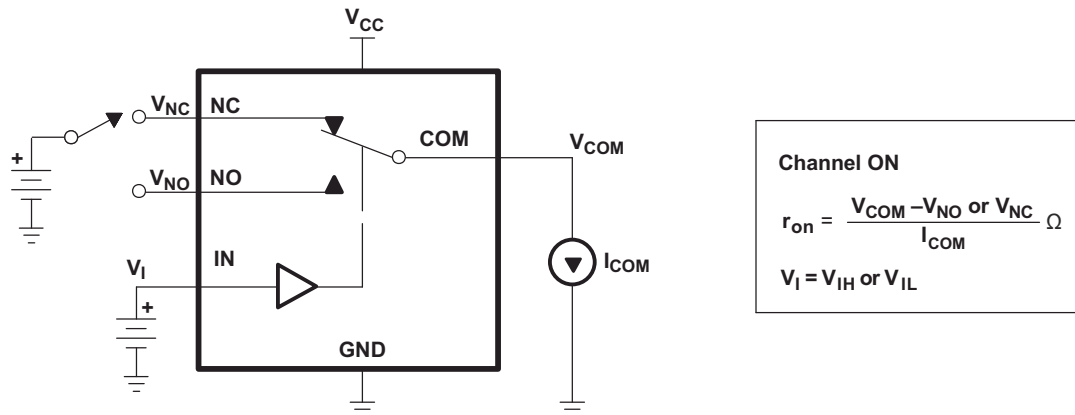


Figure 7-1. ON-State Resistance

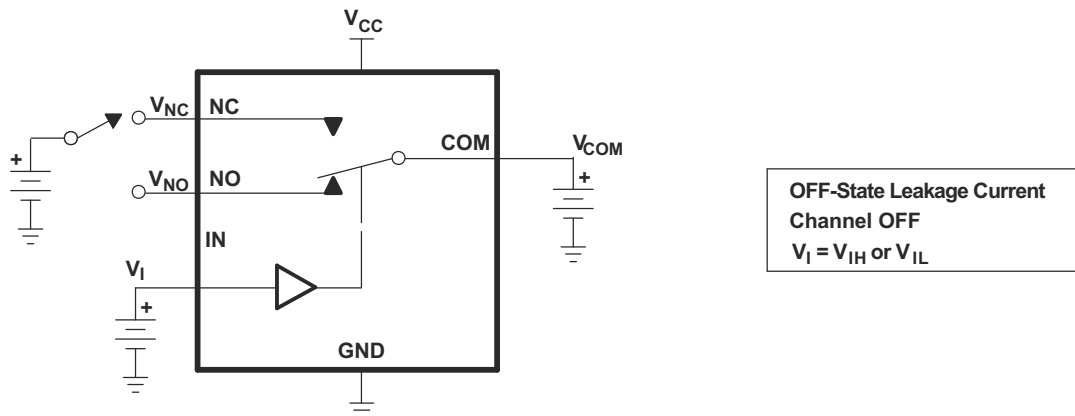


Figure 7-2. OFF-State Leakage Current ( $I_{NC(OFF)}$ ,  $I_{NC(PWROFF)}$ ,  $I_{NO(OFF)}$ ,  $I_{NO(PWROFF)}$ ,  $I_{COM(OFF)}$ ,  $I_{COM(PWROFF)}$ )

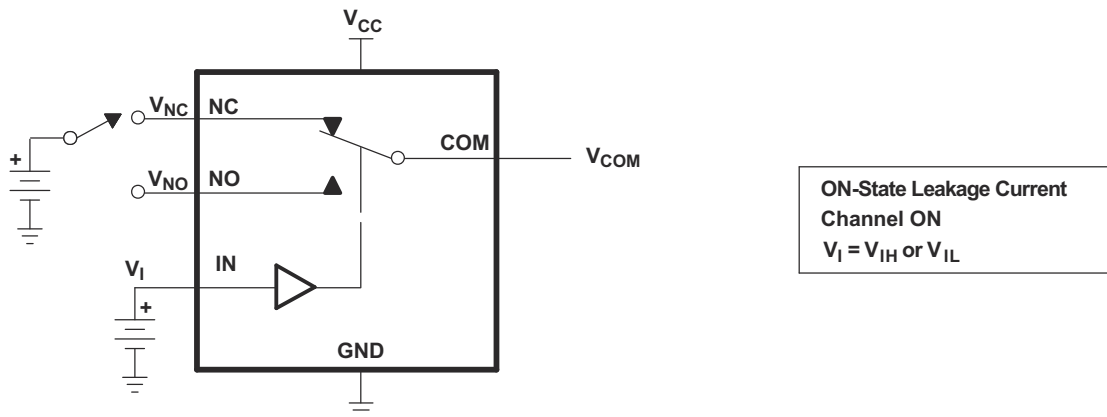


Figure 7-3. ON-State Leakage Current ( $I_{COM(ON)}$ ,  $I_{NC(ON)}$ ,  $I_{NO(ON)}$ )

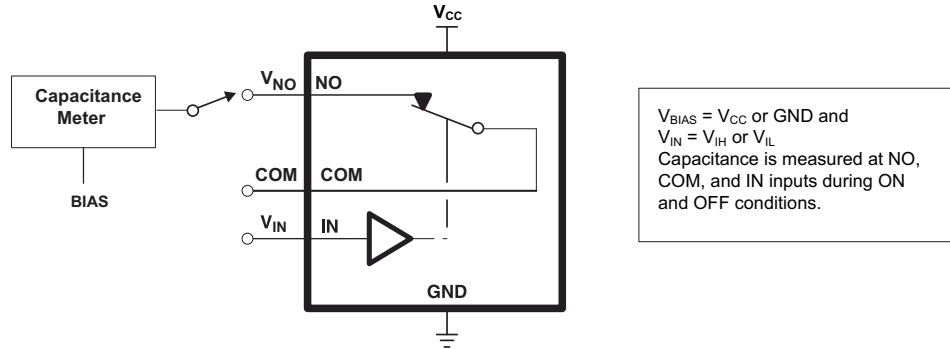
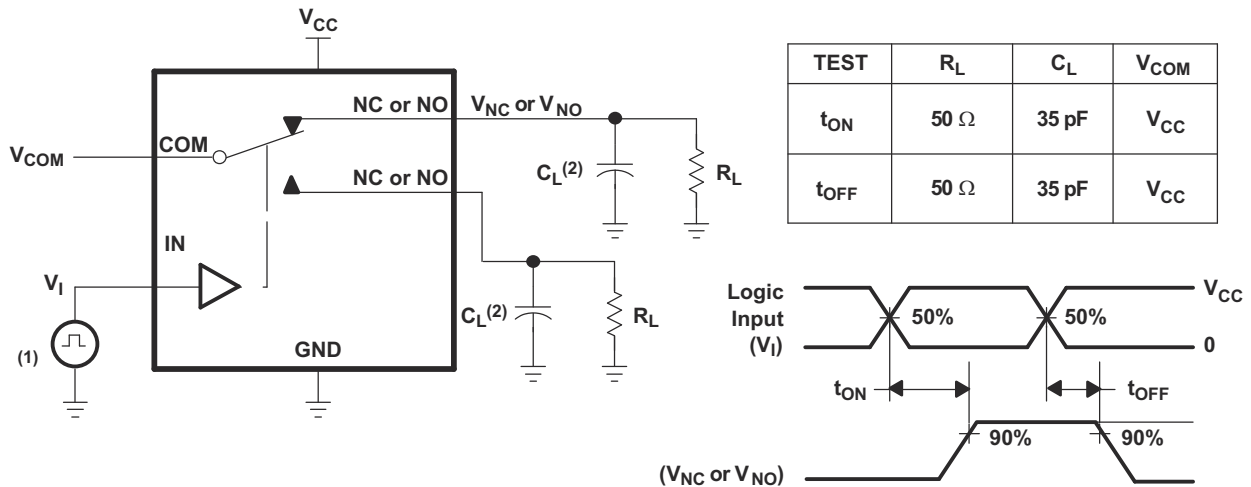
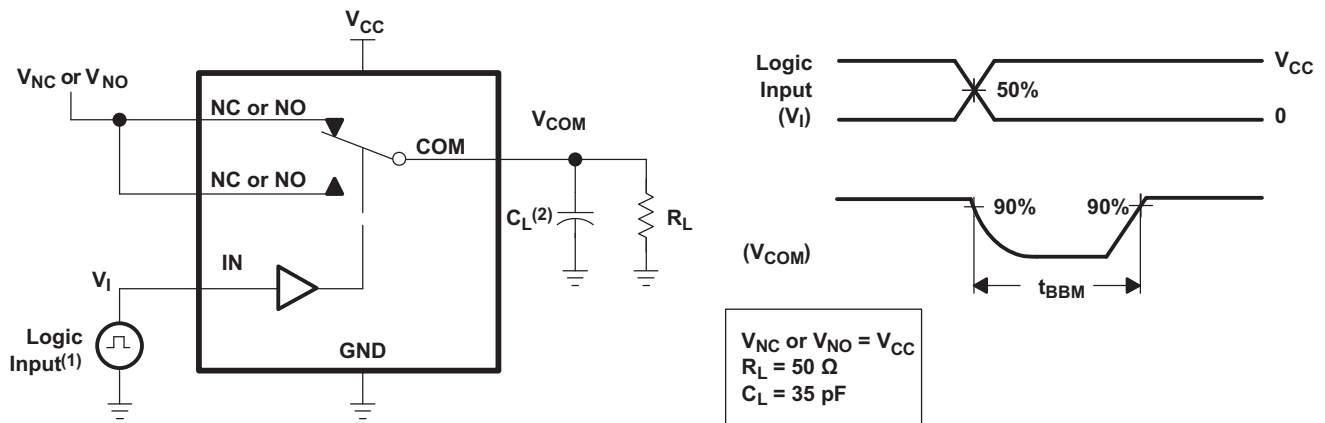


Figure 7-4. Capacitance  $C_I$ ,  $C_{NC(OFF)}$ ,  $C_{NO(OFF)}$ ,  $C_{NC(ON)}$ ,  $C_{NO(ON)}$



- A. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_r < 5$  ns,  $t_f < 5$  ns.
- B.  $C_L$  includes probe and jig capacitance.

Figure 7-5. Turn-On ( $t_{ON}$ ) and Turn-Off Time ( $t_{OFF}$ )



- A. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_r < 5$  ns,  $t_f < 5$  ns.
- B.  $C_L$  includes probe and jig capacitance.

Figure 7-6. Break-Before-Make Time ( $t_{BBM}$ )

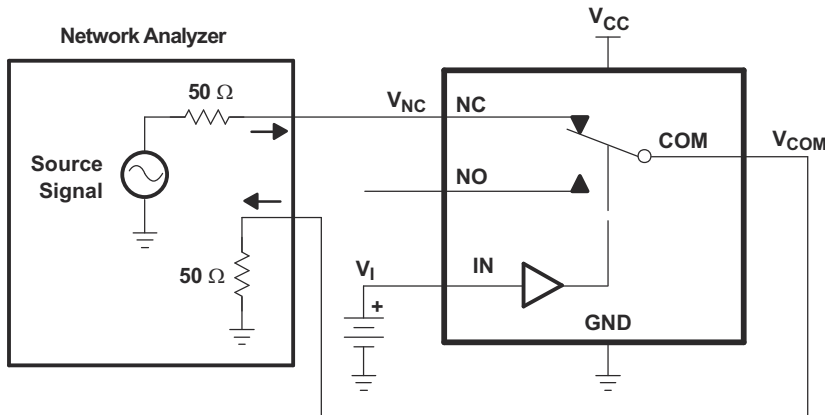


Figure 7-7. Bandwidth (BW)

Channel ON: NC to COM  
 $V_I = V_{CC}$  or GND

**Network Analyzer Setup**  
 Source Power = 0 dBm  
 (632-mV P-P at 50- $\Omega$  load)  
 DC Bias = 350 mV

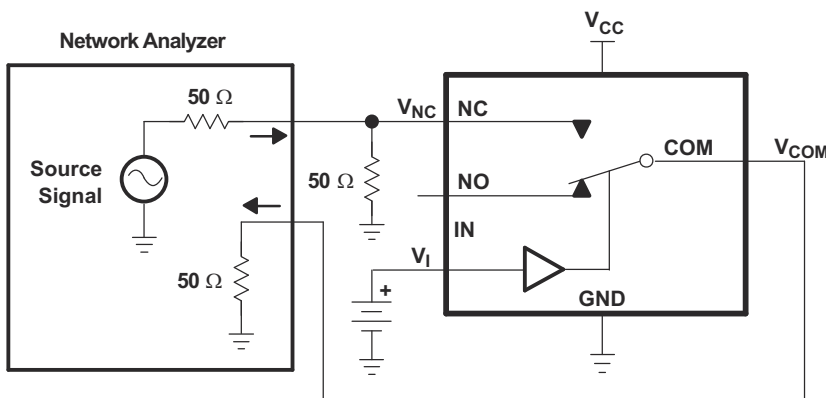


Figure 7-8. OFF Isolation ( $O_{ISO}$ )

Channel OFF: NC to COM  
 $V_I = V_{CC}$  or GND

**Network Analyzer Setup**  
 Source Power = 0 dBm  
 (632-mV P-P at 50- $\Omega$  load)  
 DC Bias = 350 mV

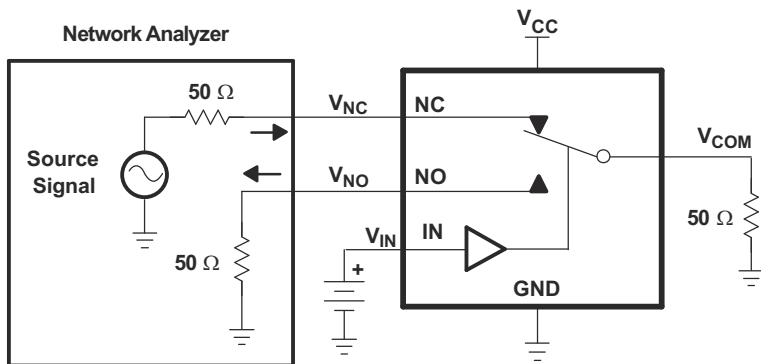
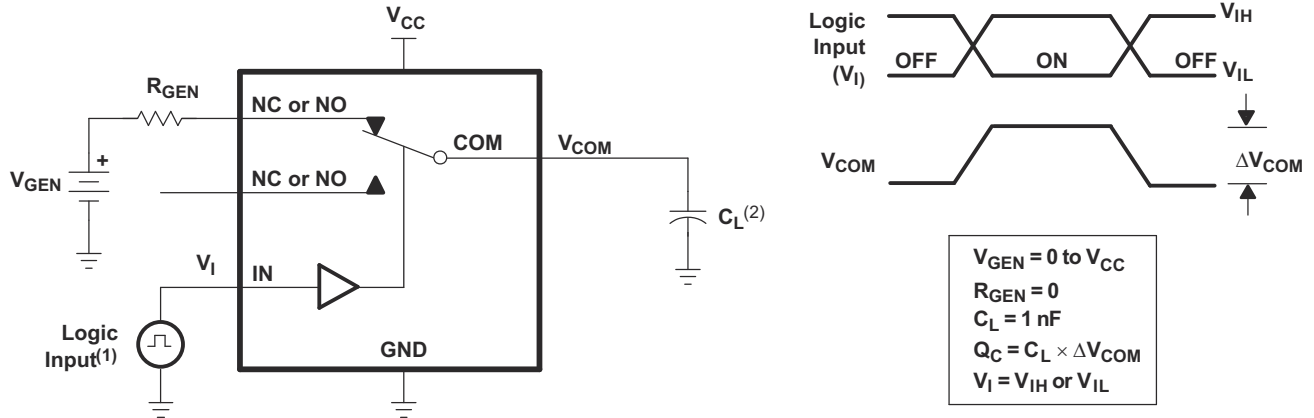


Figure 7-9. Crosstalk ( $X_{TALK}$ )

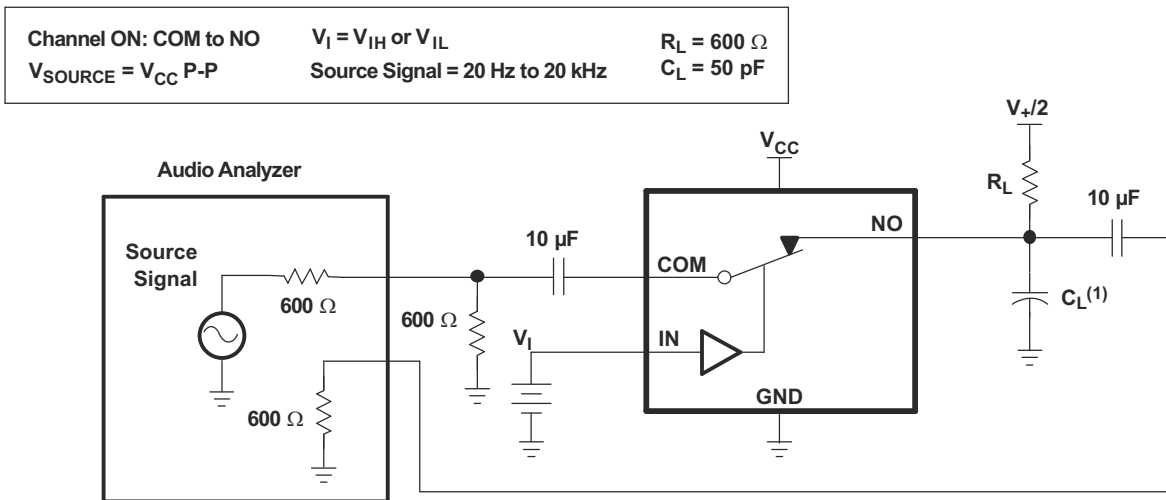
Channel ON: NC to COM  
 Channel OFF: NO to COM  
 $V_{IN} = V_{CC}$  or GND

**Network Analyzer Setup**  
 Source Power = 0 dBm  
 (632-mV P-P at 50- $\Omega$  load)  
 DC Bias = 350 mV



- A. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r < 5 \text{ ns}$ ,  $t_f < 5 \text{ ns}$ .
- B.  $C_L$  includes probe and jig capacitance.

Figure 7-10. Charge Injection ( $Q_C$ )



- A.  $C_L$  includes probe and jig capacitance.

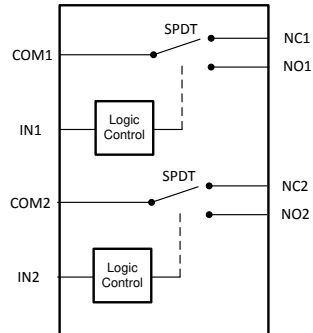
Figure 7-11. Total Harmonic Distortion (THD)

## 8 Detailed Description

### 8.1 Overview

The TS3A24159 is a 2-channel single-pole double-throw (SPDT) bidirectional analog switch that is designed to operate from 1.65 V to 3.6 V. It offers low ON-state resistance and excellent ON-state resistance matching with the break-before-make feature, to prevent signal distortion during the transferring of a signal from one channel to another. The device has excellent total harmonic distortion (THD) performance, low ON-state resistance, and consumes very low power. These are some of the features that make this device suitable for a variety of markets and many different applications.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

The TS3A24159 device is bidirectional with two single-pole, double-throw switches. Each of the two switches are controlled independently by two digital signals.

### 8.4 Device Functional Modes

**Table 8-1. Function Table**

IN	NC TO COM, COM TO NC	NO TO COM, COM TO NO
L	ON	OFF
H	OFF	ON

## 9 Application and Implementation

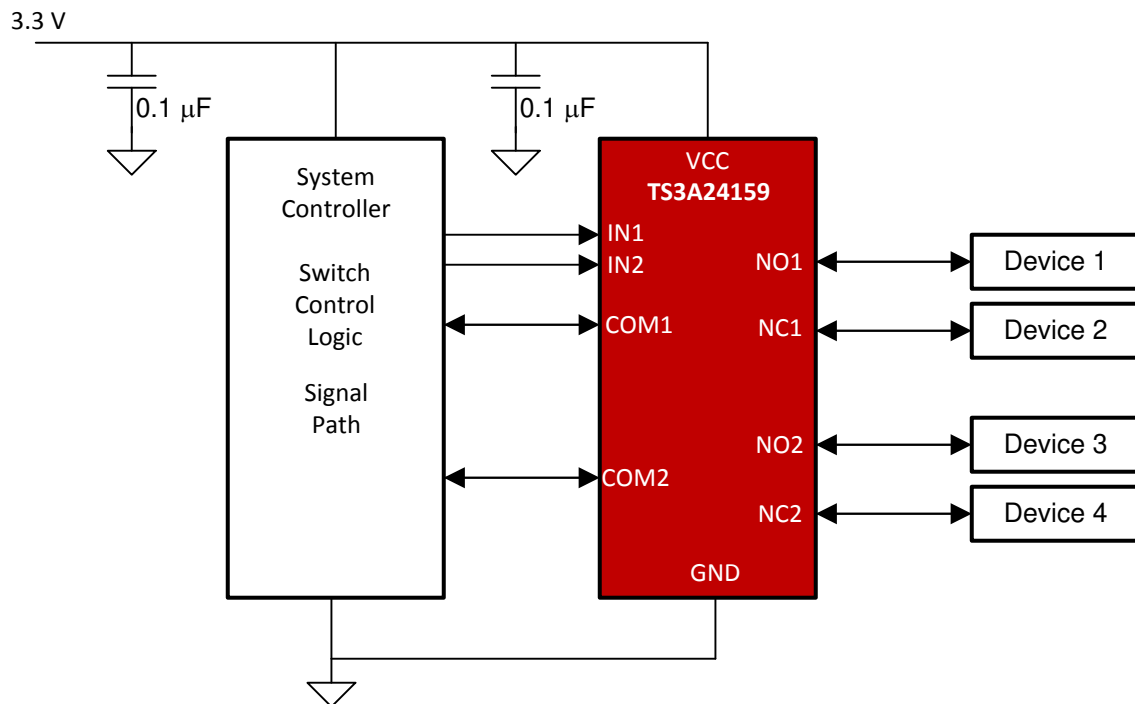
### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 9.1 Application Information

The switch of the TS3A24159 device is bidirectional. Hence, NO, NC, and COM pins can be used as both inputs or outputs.

### 9.2 Typical Application



#### 9.2.1 Design Requirements

Ensure that all of the signals passing through the switch are within the specified ranges to ensure proper performance.

**Table 9-1. Design Parameters**

		MIN	MAX	UNIT
$V_{CC}$	Supply Voltage	1.65	3.6	V
$V_{NC}$ $V_{NO}$ $V_{COM}$	Signal Voltage	0	$V_{CC}$	V
$V_{IN}$	Digital Input Voltage	0	$V_{CC}$	V

## 9.2.2 Detailed Design Procedure

The TS3A24159 device can be properly operated without any external components. However, it is recommended to connect the unused pins to ground through a 50- $\Omega$  resistor to prevent signal reflections back into the device. It is also recommended that the digital control pins (IN1 and IN2) be pulled up to  $V_{CC}$  or down to GND to avoid undesired switch positions that could result from the floating pin.

Select the appropriate supply voltage to cover the entire voltage swing of the signal passing through the switch because the TS3A24159 input/output signal swing through NO and COM are dependant of the supply voltage  $V_{CC}$ .

## 9.2.3 Application Curve

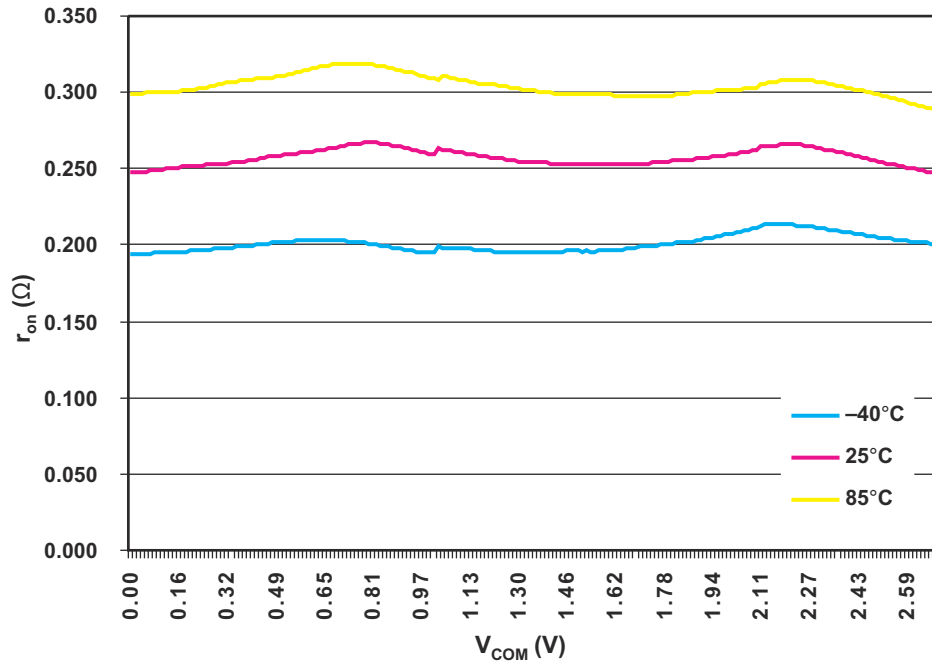


Figure 9-1.  $r_{ON}$  vs  $V_{COM}$

## 10 Power Supply Recommendations

- Proper power-supply sequencing is recommended for all CMOS devices.
- Do not exceed the absolute maximum ratings, because stresses beyond the listed ratings can cause permanent damage to the device.
- Always sequence  $V_{CC}$  on first, followed by NO or COM.
- Although it is not required, power-supply bypassing improves noise margin and prevents switching noise propagation from the  $V_{CC}$  supply to other components.
- A 0.1- $\mu$ F capacitor, connected from  $V_{CC}$  to GND, is adequate for most applications.

## 11 Layout

### 11.1 Layout Guidelines

To ensure reliability of the device, following common printed-circuit board layout guidelines is recommended. Bypass capacitors must be used on power supplies. Short trace lengths should be used to avoid excessive loading.

### 11.2 Layout Example

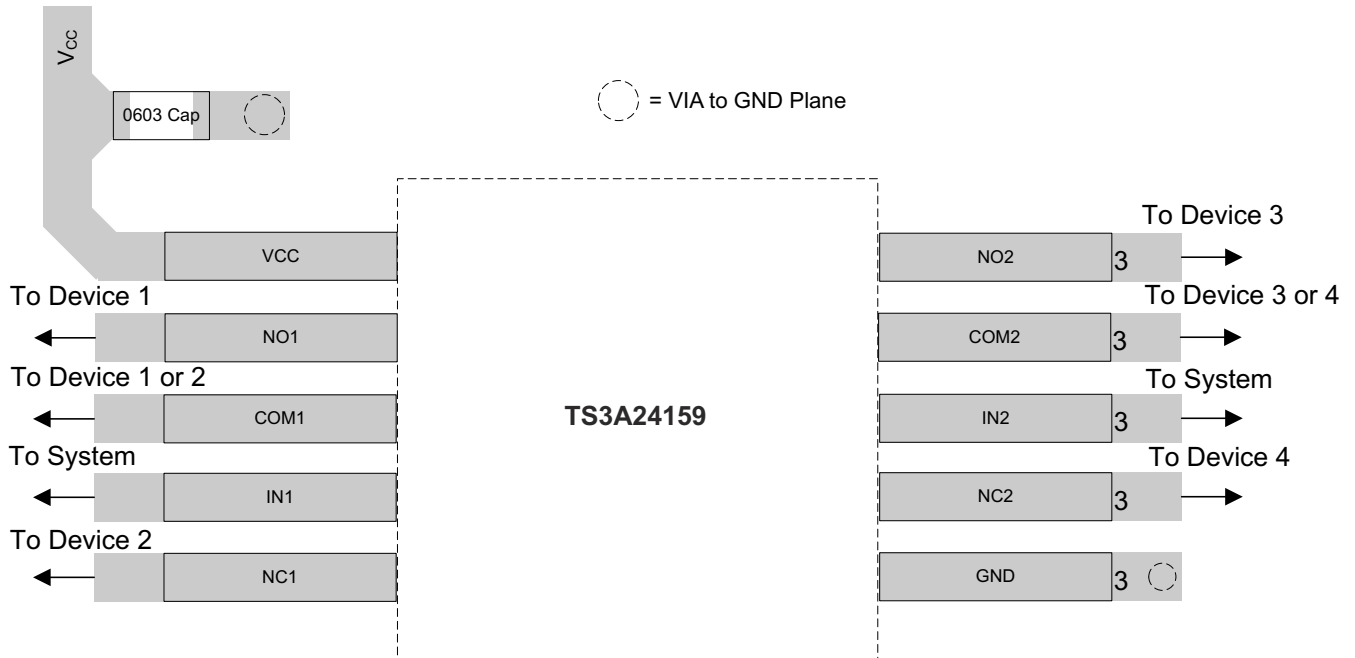


Figure 11-1. Layout Example

## 12 Device and Documentation Support

### 12.1 Documentation Support

#### 12.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, [Implications of Slow or Floating CMOS Inputs application note](#)

### 12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](#). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 12.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 12.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

### 12.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 12.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TS3A24159DGSR	ACTIVE	VSSOP	DGS	10	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(L8Q, L8R)	<a href="#">Samples</a>
TS3A24159DGSRG4	LIFEBUY	VSSOP	DGS	10	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(L8Q, L8R)	
TS3A24159DRCR	ACTIVE	VSON	DRC	10	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZWS	<a href="#">Samples</a>
TS3A24159DRCRG4	LIFEBUY	VSON	DRC	10	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZWS	
TS3A24159YZPR	ACTIVE	DSBGA	YZP	10	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	L87	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS3A24159DGSR	VSSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TS3A24159DRCR	VSON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
TS3A24159YZPR	DSBGA	YZP	10	3000	178.0	9.2	1.49	1.99	0.63	4.0	8.0	Q2

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS3A24159DGSR	VSSOP	DGS	10	2500	358.0	335.0	35.0
TS3A24159DRCR	VSON	DRC	10	3000	356.0	356.0	35.0
TS3A24159YZPR	DSBGA	YZP	10	3000	220.0	220.0	35.0

# DGS0010A



# PACKAGE OUTLINE

## VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4221984/A 05/2015

### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187, variation BA.

# EXAMPLE BOARD LAYOUT

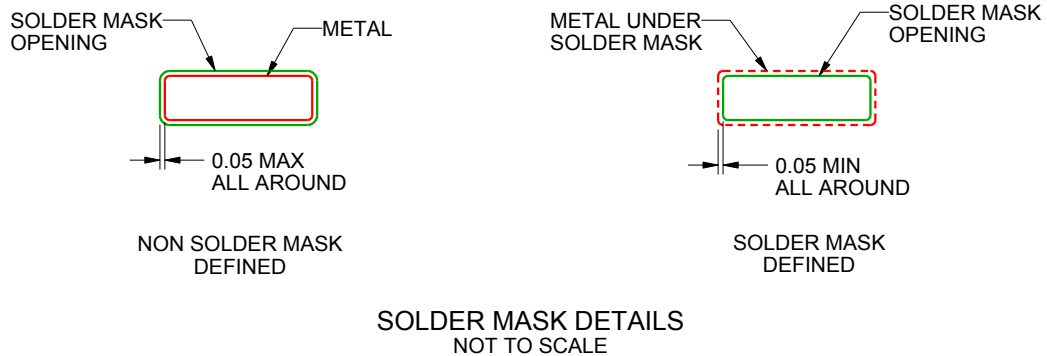
DGS0010A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:10X



SOLDER MASK DETAILS  
NOT TO SCALE

4221984/A 05/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DGS0010A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:10X

4221984/A 05/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

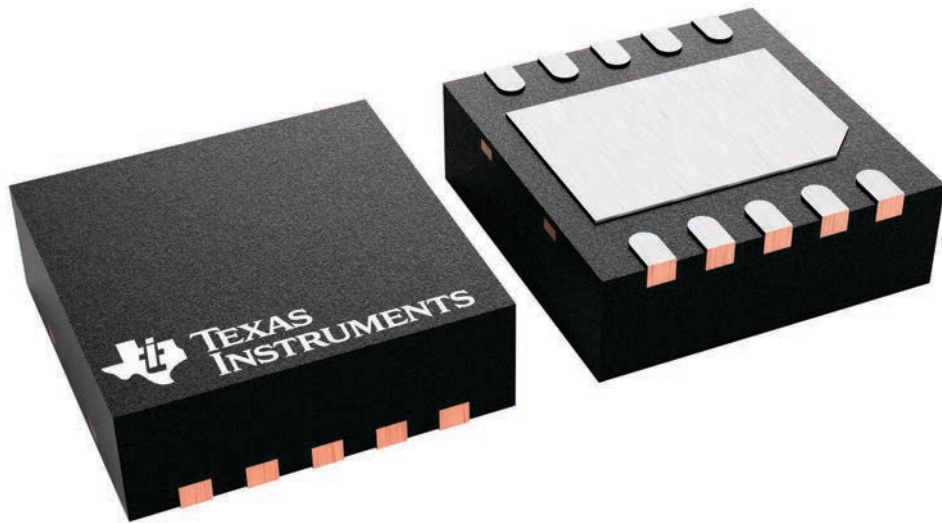
**DRC 10**

**VSON - 1 mm max height**

3 x 3, 0.5 mm pitch

PLASTIC SMALL OUTLINE - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4226193/A

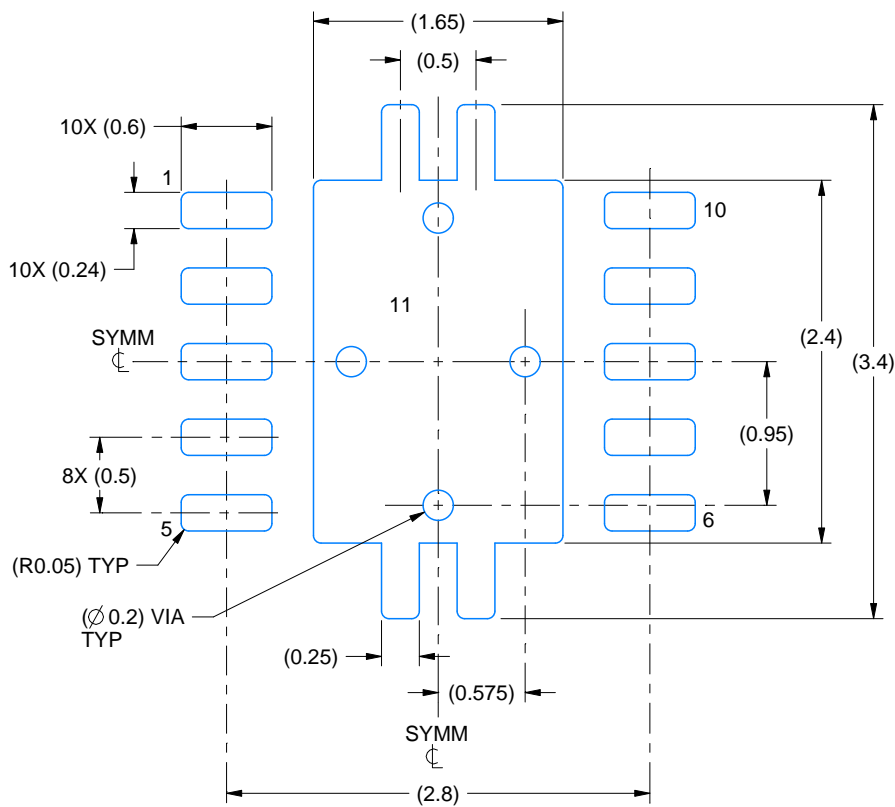


# EXAMPLE BOARD LAYOUT

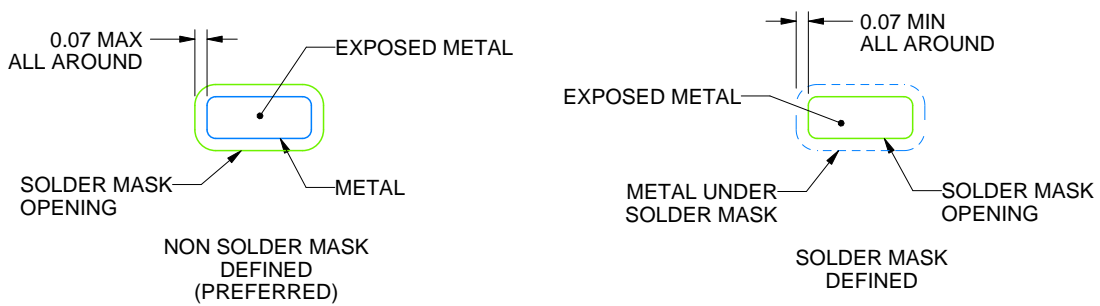
DRC0010J

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:20X



SOLDER MASK DETAILS

4218878/B 07/2018

NOTES: (continued)

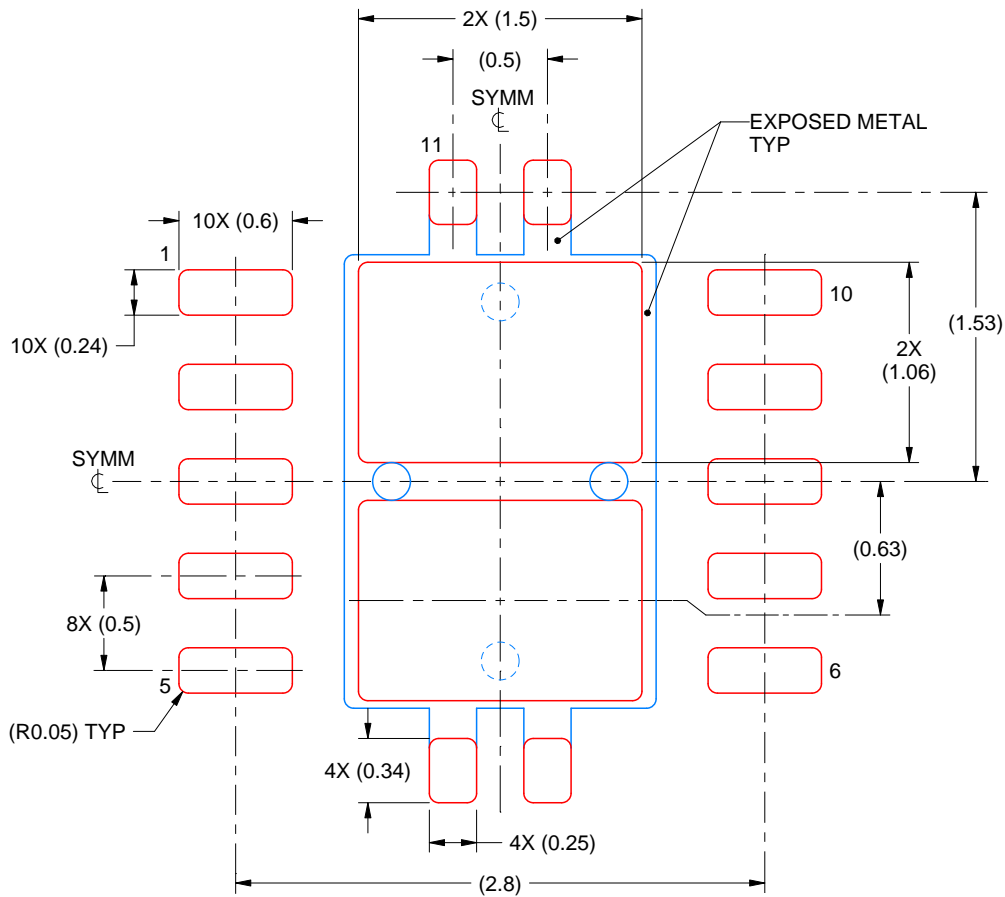
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

DRC0010J

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 11:  
80% PRINTED SOLDER COVERAGE BY AREA  
SCALE:25X

4218878/B 07/2018

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

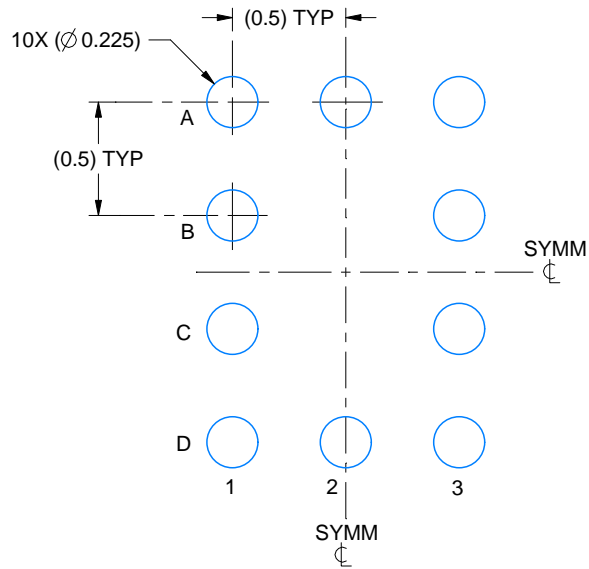


# EXAMPLE BOARD LAYOUT

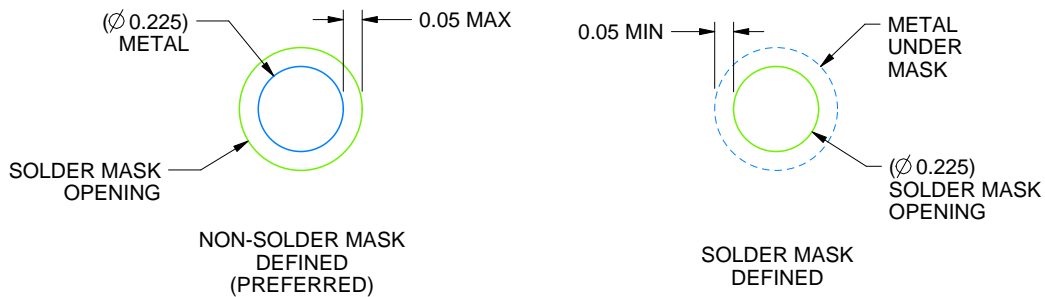
YZP0010

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE  
SCALE:30X



SOLDER MASK DETAILS  
NOT TO SCALE

4219350/B 11/2017

NOTES: (continued)

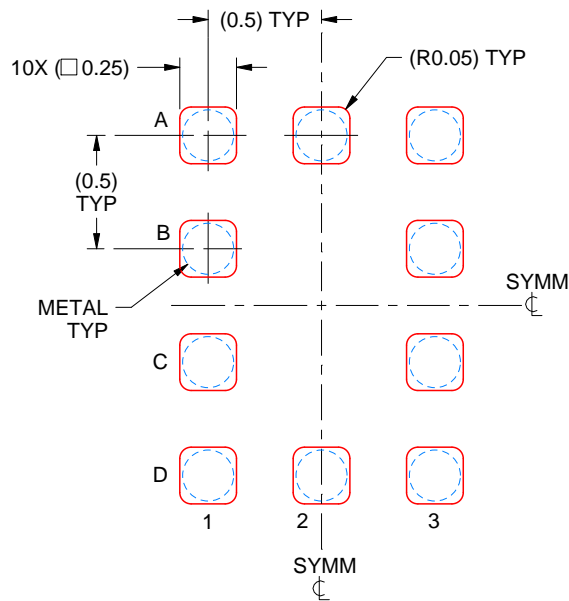
- 3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SBVA017 ([www.ti.com/lit/sbva017](http://www.ti.com/lit/sbva017)).

# EXAMPLE STENCIL DESIGN

YZP0010

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:30X

4219350/B 11/2017

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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